



EV318282279

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. .... 09/148,723  
Filing Date ..... September 3, 1998  
Inventor ..... Warren M. Farnworth et al.  
Assignee ..... Micron Technology, Inc.  
Group Art Unit ..... 3729  
Examiner ..... A.D. Tugbang  
Attorney's Docket No. .... MI22-981  
Title: Methods of Bonding Solder Balls to Bond Pads on a Substrate

RESPONSE TO JUNE 18, 2003 OFFICE ACTION

#43/J  
gwd9/30/03

To: Mail Stop Non-Fee Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

From: D. Brent Kenady  
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Responsive to the Office Action dated June 18, 2003, Applicant amends and remarks as follows:

AMENDMENTS

Underlines indicate insertions and ~~strikeouts~~ indicate deletions.